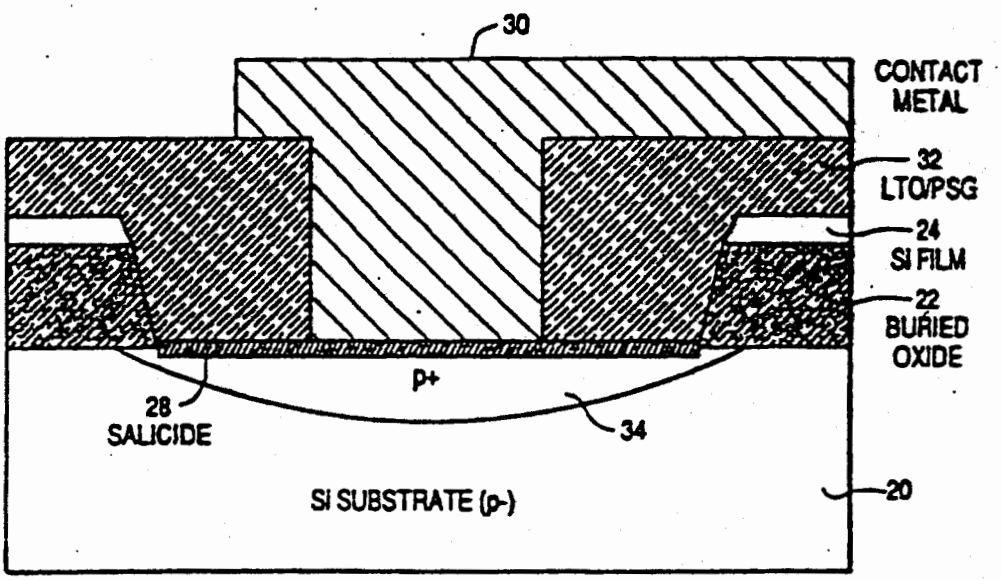


Fig. 1 Prior Art

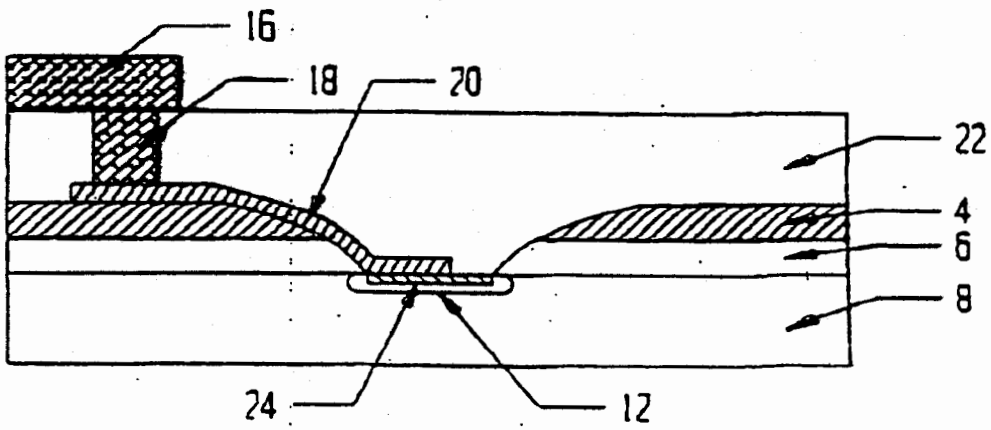


Fig. 2 Prior Art

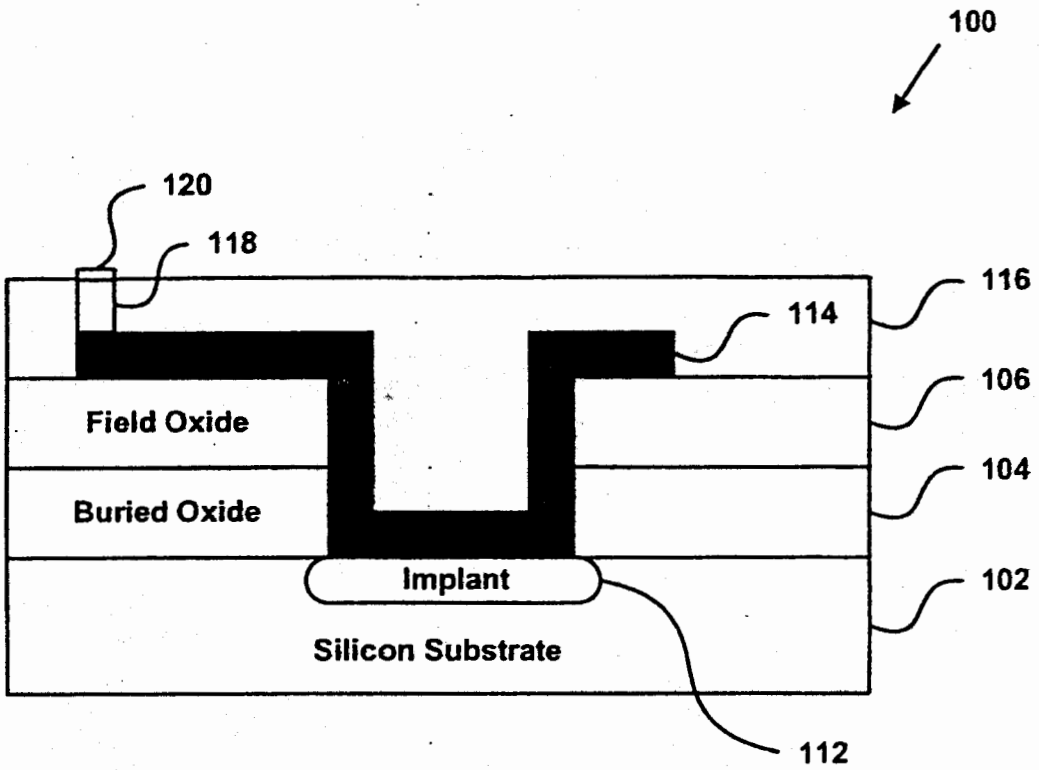

100
120
118
116
114
106
Field Oxide
104
Buried Oxide
Implant
102
Silicon Substrate
112

Fig. 3

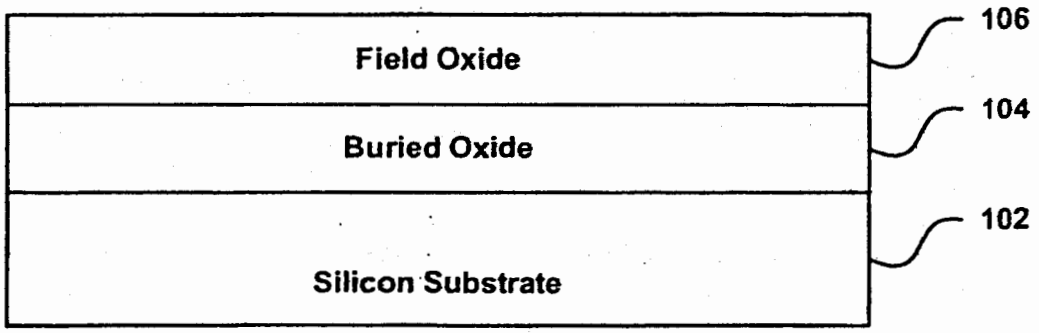

106
Field Oxide
104
Buried Oxide
102
Silicon Substrate

Fig. 4

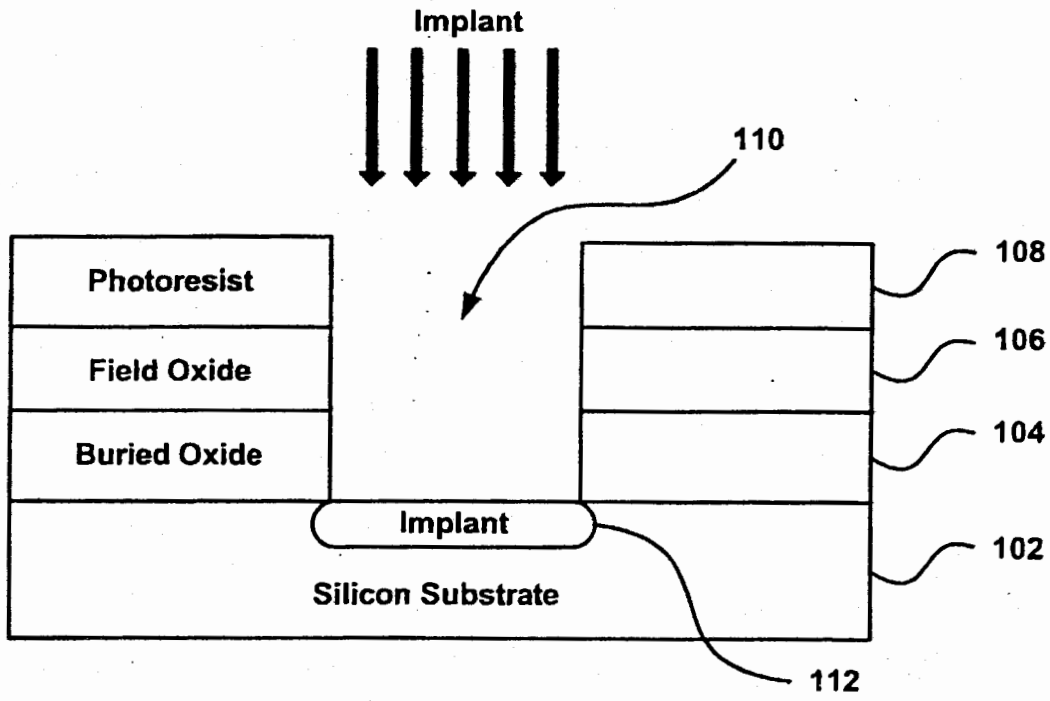

Implant
110
Photoresist
Field Oxide
Buried Oxide
Implant
Silicon Substrate
108
106
104
102
112

Fig. 5

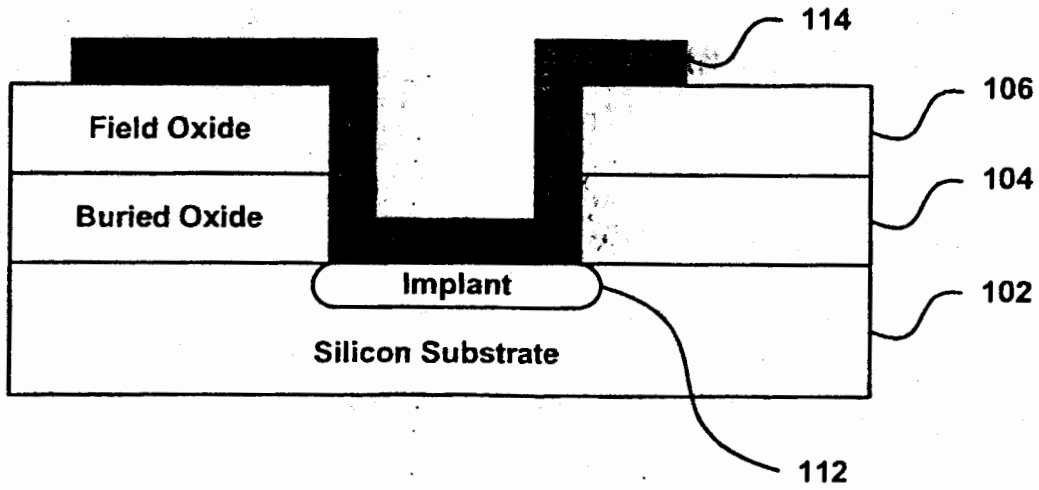

114
Field Oxide
Buried Oxide
Implant
Silicon Substrate
106
104
102
112

Fig. 6

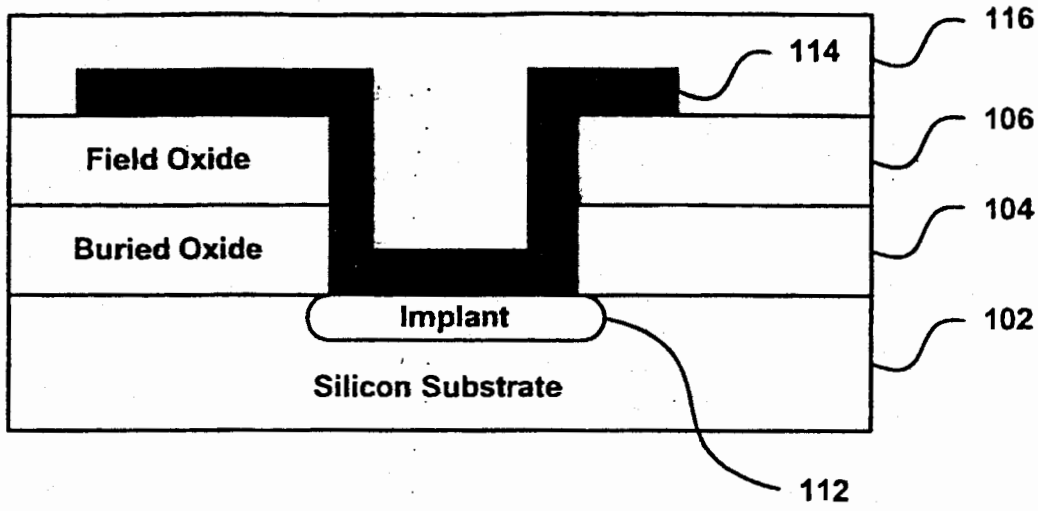

116
114
106
Field Oxide
104
Buried Oxide
Implant
102
Silicon Substrate
112

Fig. 7

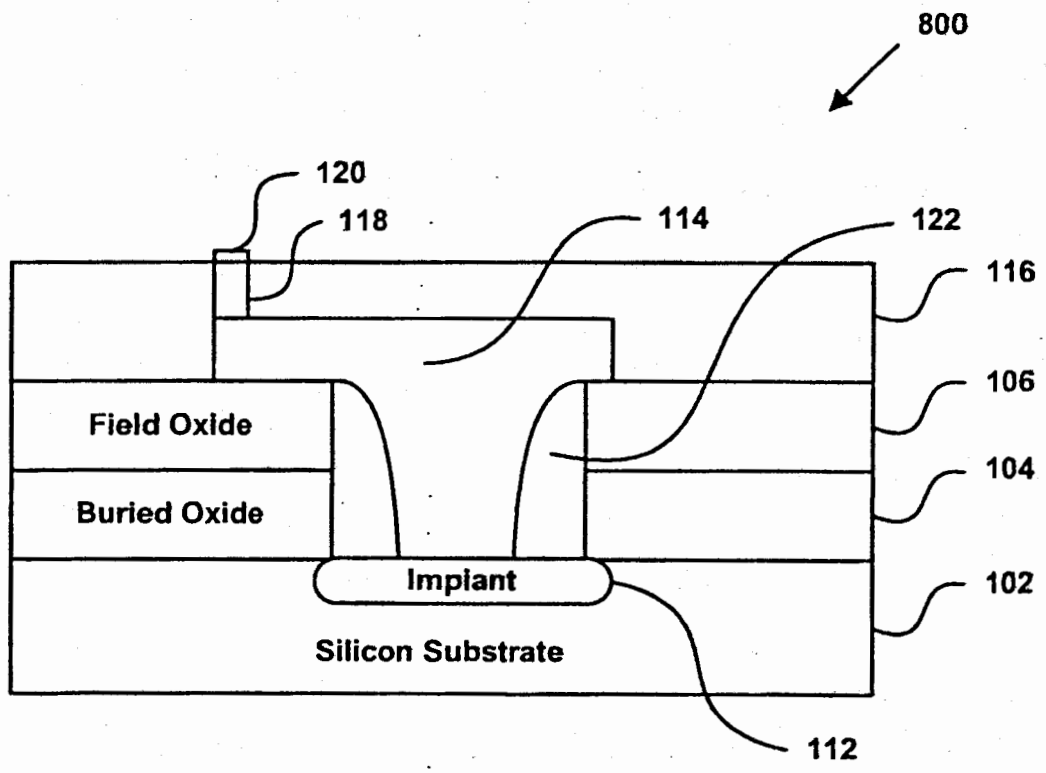

800
120
118
114
122
116
106
Field Oxide
104
Buried Oxide
Implant
102
Silicon Substrate
112

Fig. 8

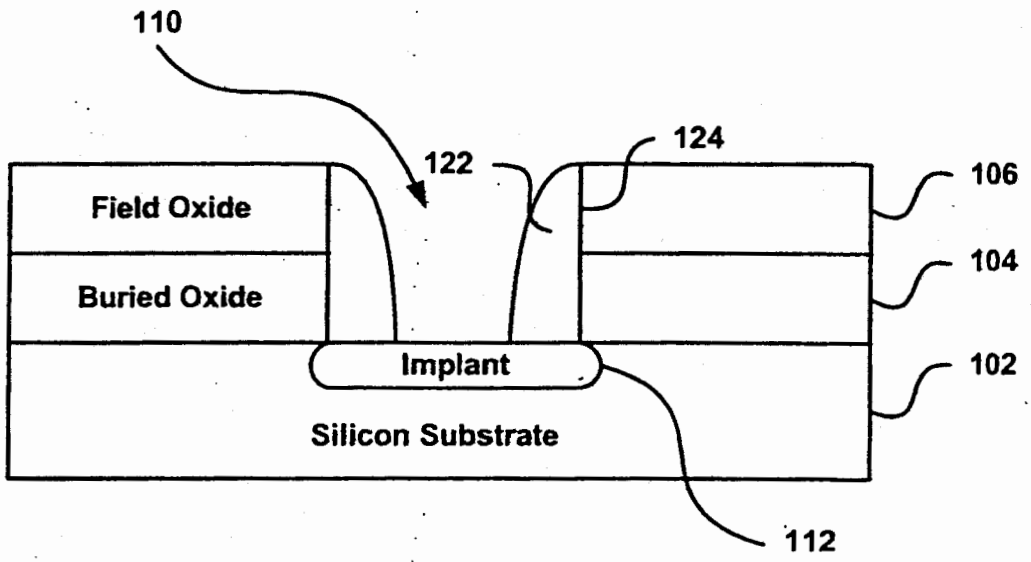

110
122
124
106
104
102
Field Oxide
Buried Oxide
Implant
Silicon Substrate
112

Fig. 9

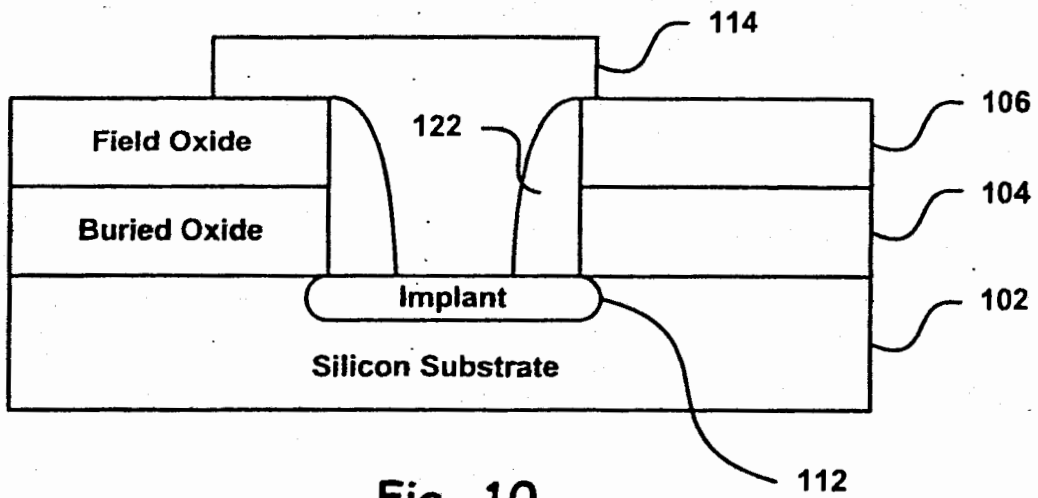

114
122
106
104
102
Field Oxide
Buried Oxide
Implant
Silicon Substrate
112

Fig. 10

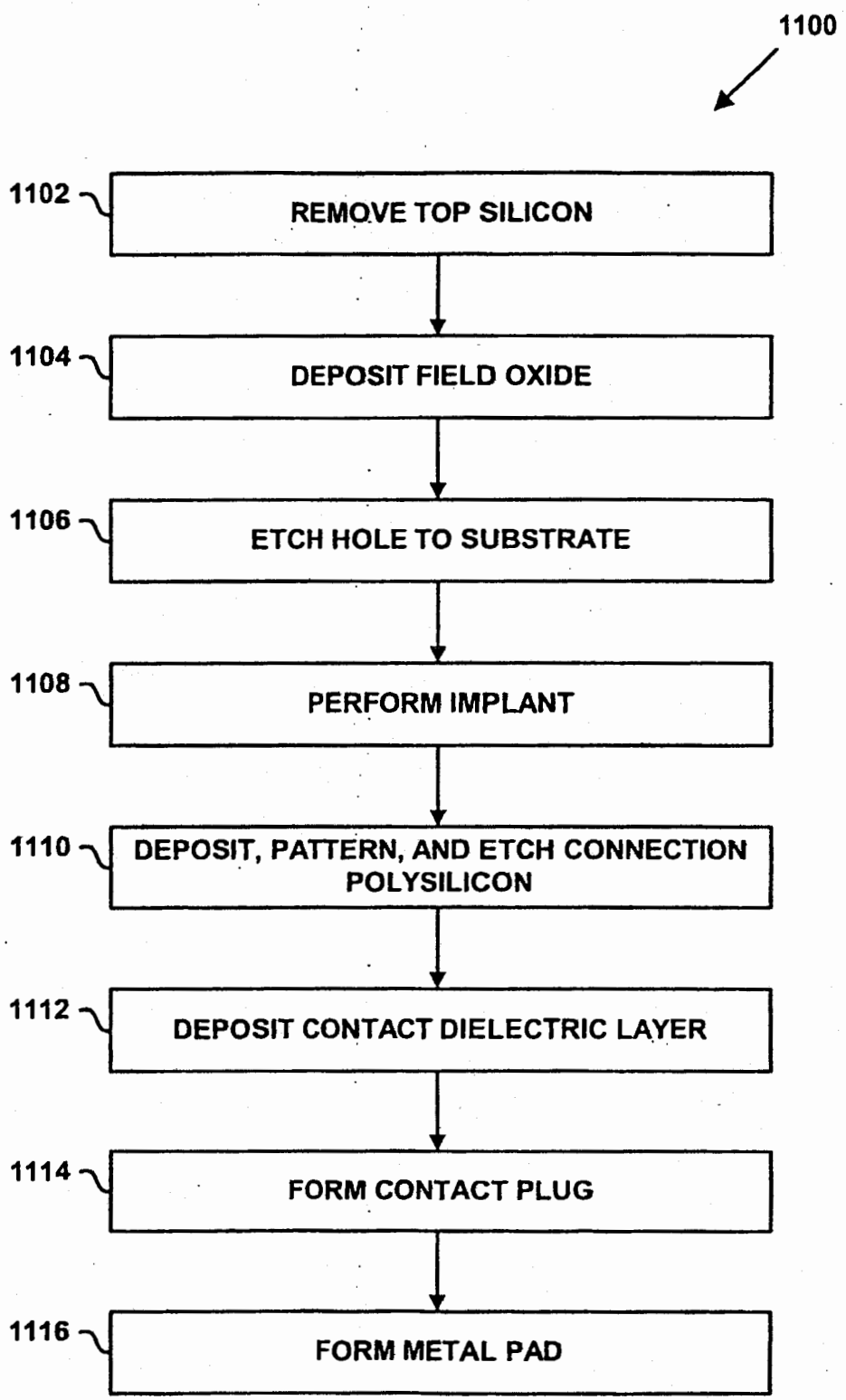

1100
1102
REMOVE TOP SILICON
1104
DEPOSIT FIELD OXIDE
1106
ETCH HOLE TO SUBSTRATE
1108
PERFORM IMPLANT
1110
DEPOSIT, PATTERN, AND ETCH CONNECTION POLYSILICON
1112
DEPOSIT CONTACT DIELECTRIC LAYER
1114
FORM CONTACT PLUG
1116
FORM METAL PAD

Fig. 11

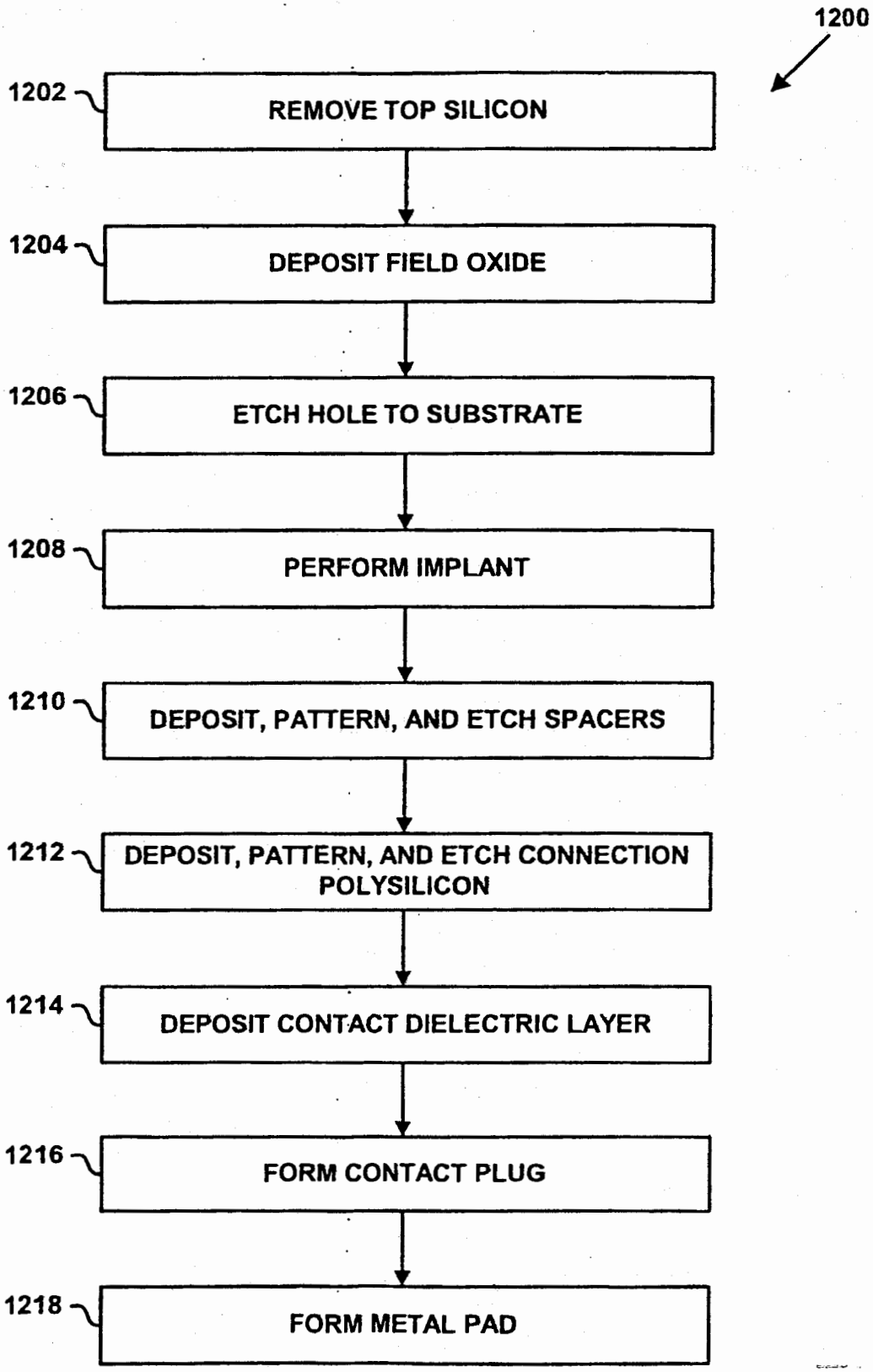

1200
1202
REMOVE TOP SILICON
1204
DEPOSIT FIELD OXIDE
1206
ETCH HOLE TO SUBSTRATE
1208
PERFORM IMPLANT
1210
DEPOSIT, PATTERN, AND ETCH SPACERS
1212
DEPOSIT, PATTERN, AND ETCH CONNECTION POLYSILICON
1214
DEPOSIT CONTACT DIELECTRIC LAYER
1216
FORM CONTACT PLUG
1218
FORM METAL PAD

Fig. 12